

FORM PTO-1449 (Modified for Citation of Foreign  
Cited References)ATTY. DOCKET NO.  
USA.02.022SERIAL NO.  
10/091086LIST OF INFORMATION PROVIDED  
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APR 15 2002

(Use several sheets if necessary)

APPLICANT  
STEWART, et alFILING DATE  
March 5, 2002GROUP  
Unknown

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

Examiner Initial		Document No.	Date*	Patentee	Date* Cited in Foreign Patent Office
TT	AA	5,930,889	8/3/1999	Klein	
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TT	AD	5061549	10/29/1991	Shores	
TT	AE	5372883	12/13/1994	Shores	
TT	AF	6297560	10/02/2001	Capote et al	
TT	AG	6265776	7/24/2001	Gilleo	

## FOREIGN PATENT DOCUMENTS

		Document No.	Country	Date*	Date* Cited in Foreign P.O.	English Translation Yes No
	FA					
	FB					

## OTHER PUBLICATIONS (AUTHOR, TITLE, DATE\*, PLACE OF PUBLICATION, PERTINENT PAGES)

			Date* Cited in Foreign P.O.	English Translation Yes No
TT	PA	Adamson, S.J., "CSP and flip chip underfill," Advanced Packaging, June 2001, pp. 37-44.		
TT	PB	Johnson, Zane, "BGA Underfills" Advanced Packaging, December 2001, pp. 29-33.		
TT	PC	Alpha Microelectronic: Staystik Adhesive for Mag Heads, [internet] Retrieved on December 19, 2001, URL: www.us-tech.com/april99/prods/cmp/cmp016.htm		
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*Thien K. M.*

DATE CONSIDERED

04/08/04

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## OTHER PUBLICATIONS (AUTHOR, TITLE, DATE\*, PLACE OF PUBLICATION, PERTINENT PAGES)

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TT	PL	Chapter C: Conductive Polymers, Level 1: Introduction [internet], last updated on 2000-09-07; URL: <a href="http://extra.ivf.se/ngl/C-polymerBonding/ChapterC.htm">http://extra.ivf.se/ngl/C-polymerBonding/ChapterC.htm</a>			
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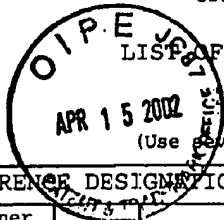
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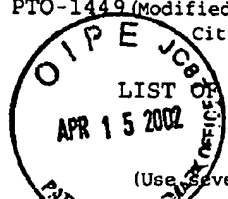
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 LIST OF INFORMATION PROVIDED BY APPLICANT (Use several sheets if necessary)			APPLICANT STEWART, et al			
			FILING DATE March 5, 2002		GROUP Unknown	
REFERENCE DESIGNATION			U.S. PATENT DOCUMENTS			
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OTHER PUBLICATIONS (AUTHOR, TITLE, DATE*, PLACE OF PUBLICATION, PERTINENT PAGES)						
			Date* Cited in Foreign P.O.	English Translation Yes No		
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TT	PW	Fine, P., "Flip Chip Underfill Flow Characteristics and Prediction," 1999 Electronic Components and Technology Conference, 0-7803-5234-3/99				
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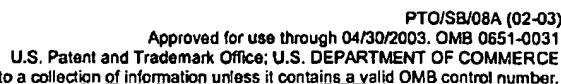
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Application Number	10/091, 086
Filing Date	03/05/2002
First Named Inventor	Stewart, Steven L.
Art Unit	
Examiner Name	
Attorney Docket Number	US.01.012

Sheet	1	of	2
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## U. S. PATENT DOCUMENTS

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**FOREIGN PATENT DOCUMENTS**

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Examiner Initials*	Cite No.	Foreign Patent Document	Publication Date	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear	Footnote
		Country Code <sup>3</sup> Number <sup>4</sup> Kind Code <sup>5</sup> (# known)	MM-DD-YYYY			
TT		EP 0729182A	08-28-1996	Matsushita Electric Inc		
TT		DE 19822470A	12-09-1999	Litton Precision Product		
TT		JP 08250835A	09-27-1996	NEC Corp		
TT		JP 10335527A	12-18-1998	NEC Corp		
TH		JP 03036788A	02-18-1991	Murata Mfg Co Ltd		
TT		JP 04249307A	09-04-1992	Nippon Chemicon Corp		

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PTO/SB/08A (02-03)

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		Country Code <sup>3</sup> -Number <sup>4</sup> -Kind Code <sup>5</sup> (if known)	MM-DD-YYYY			
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TI		JP 57068053 A	04-26-1982	Seiko Epson Corp		
TI		JP 04352491 A	12-7-1992	Matsushita Electric Ind		

Examiner Signature	<i>Thien Tran</i>	Date Considered	09/08/04
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